LOPEC
March 2–4, 2027 | Messe München
Lopec.com

Press release | 09.11.2026

LOPEC 2027 bringing research and manufacturing together

- **Growing exhibition**
- **Conference focused on industrial scaling**
- **User sessions with new format**

Flexible and printed electronics open up further applications: In addition to the automotive industry, healthcare, and packaging, there is also a growing focus on defense and aerospace. The OE-A describes this development in its current Roadmap. As the number of potential applications rises, one question is becoming increasingly important: How can the technology be scaled so that it is reproducible, fast, reliable, and cost-effective?

This is where LOPEC 2027 at the ICM – International Congress Center, Messe München comes in. The conference will take place from March 2 to 4, and the trade fair on March 3 and 4. LOPEC brings together manufacturers, material suppliers, mechanical engineering companies, research institutions, and users at the event. At the same time, it provides an overview of technologies and applications and combines it with professional exchange on their industrial implementation.

Added space thanks to international demand

The registration figures look promising: The amount of exhibition space booked is currently slightly higher than it was at the same time last year.
The strong international demand is particularly encouraging. Bookings from foreign companies are significantly higher than last year.

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“We are delighted with the positive latest figures and the strong demand from abroad. At the same time, the abstract submissions for the LOPEC conference reveal a lot of interest in the topic of scaling, in the broadest sense. Printed electronics is used in industrial applications. The priority now is to cost-effectively bring further applications into series production. That requires materials, processes, and system integration to fit together. LOPEC is where the right partners meet directly,” says Armin Wittmann, Exhibition Director of LOPEC.

Scaling for series production

A glance at the submitted abstracts is enough to show just how much research and industry are focusing on the issue of scaling. At the Technical Conference, most of the submissions fall under the category “Upscaling Production and Manufacturing,” while the Scientific Conference centers on “Scalable, Sustainable, Innovative Processes.” That’s a clear sign that the industry is focused on mass production. The panel discussion ties in with that. A high-profile international panel of industry representatives will discuss what it takes to successfully scale printed electronics. There are three key factors to consider: the maturity of the business models, production readiness, and the level of technological maturity. After all, it’s only when the market, production, and technology work together that a functioning technology becomes an industrial solution.

User sessions become more specific

In addition to the manufacturing topics, the LOPEC Conference will be focusing more on key application areas. At the next event, the healthcare, defense, security, and aerospace sectors will be highlighted in special application sessions.

The range of possible applications extends from near-body sensors and smart textiles to functional surfaces. Thin and flexible components can perform measurement, heating, or lighting functions and adapt to different shapes. Here, the user sessions follow on from the conference’s technical and scientific sessions.

From materials to applications

LOPEC combines trade fair and conference under one roof. The conference delves into technological and scientific issues, while the trade fair brings the solutions tangibly to life. The entire value chain is covered: from functional materials and manufacturing systems to components, system integration, and the finished application. That allows trade visitors to better evaluate different approaches, compare solutions, and talk with potential development and production partners.

More information can be found at lopec.com

LOPEC
LOPEC () is the world's leading event for printed electronics. The combination of exhibition and conference covers the complexity and dynamism of this young industry perfectly. LOPEC is organized jointly by the OE-A (Organic and Printed Electronics Association) and Messe München GmbH. The next event will take place from March 2 to 4, 2027 at Messe München's International Congress Center.

Messe München
As one of the world's leading trade fair organizers, Messe München presents the world of tomorrow at its around 90 international trade fairs. These include 14 of the world's leading trade fairs such as bauma, BAU, IFAT, and electronica. Its portfolio comprises trade fairs for capital and consumer goods, as well as for new technologies. Together with its 1,300 employees in the group and the affiliated companies, it organizes trade fairs in China, India, Brazil, South Africa, Turkey, Singapore, Vietnam, Hong Kong, Thailand, and the U.S. With an international network of affiliated companies and foreign representatives, Messe München is active worldwide. The more than 150 events held annually attract around 50,000 exhibitors and around three million visitors in Germany and abroad. That makes Messe München an important economic driver, triggering purchasing power effects in the billions.

OE-A – Advancing the Flexible and Printed Electronics Industry
The OE-A is the world's leading industrial association for flexible, and printed electronics. It represents the entire value chain of this industry. Its members are world-leading companies and institutions, from research and development institutes to mechanical engineers and material manufacturers to producers and end users. 180 companies from Europe, Asia, North America, and Africa work together in the OE-A to promote the development of a competitive infrastructure for the production of flexible and printed electronics. OE-A is an international working group within VDMA. www.oe-a.org